



Material Content Data Sheet



Sales Product Name		BTS7002-1EPP		Issued		9. January 2019		
MA#		MA004430230						
Package		PG-TSDSO-14-22		Weight*		65.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.192	3.35	3.35	33473	33473
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.038	0.06		576	
	non noble metal	iron	7439-89-6	0.754	1.15		11516	
wire	non noble metal	copper	7440-50-8	30.617	46.76	47.98	467608	479844
	non noble metal	copper	7440-50-8	0.773	1.18	1.18	11799	11799
	encapsulation	organic material	carbon black	1333-86-4	0.084	0.13		1282
plastics	plastics	epoxy resin	-	3.274	5.00		50003	
		inorganic material	silicondioxide	60676-86-0	24.625	37.61	42.74	376092
leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25072	25072
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12463	12463
glue	plastics	epoxy resin	-	0.114	0.17		1745	
		noble metal	silver	7440-22-4	0.539	0.82	0.99	8227
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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